

# ECN-360A-<sup>HM65</sup> D2550

Fanless Embedded System with Intel® Solution



## Features

- **On-board CPU**
  - » ECN-360A-HM65: Intel® Celeron® 847E dual-core 1.1 GHz
  - » ECN-360A-D2550: Intel® Atom™ D2550 dual-core 1.86 GHz
- **Rich video output solution**
  - » ECN-360A-HM65: 2 x HDMI + 1 x VGA
  - » ECN-360A-D2550: 2 x VGA
- **Ruggedized embedded computer**
  - » Supports -10°C~60°C (w/ SSD, air flow)



## Specifications

Model Name		ECN-360A-HM65	ECN-360A-D2550
Chassis	Color	Black	Black
	Dimensions (WxDxH) (mm)	255 x 130 x 63	255 x 130 x 63
	System Fan	Fanless	Fanless
	Chassis Construction	SECC	SECC
Motherboard	Motherboard Model	NANO-HM651-847E	NANO-CV-D25502
	SBC Size (mm)	EPIC, 165 x 115	EPIC, 165 x 115
	CPU	Intel® Celeron® 847E dual-core 1.1 GHz	Intel® Atom™ dual-core D2550 1.86GHz
	Chipset	Intel® HM65	Intel® NM10
	System Memory	2 x 204-pin DDR3 SDRAM SO-DIMM (system max: 8 GB) Pre-installed 4 GB DDR3 memory	1 x 204-pin DDR3 SDRAM SO-DIMM (system max: 4 GB) Pre-installed 2 GB DDR3 memory
Storage	Hard Drive	1 x 2.5" SATA HDD bay	1 x 2.5" SATA HDD bay
I/O Interfaces	USB 3.0	2	0
	USB 2.0	2	6
	Ethernet	2 x Realtek RTL8111E PCIe GbE controller with ASF 2.0 support	2 x Realtek RTL8111E with ASF 2.0 support
	COM Port	2 x RS-232 1 x RS-422/485	3 x RS-232 1 x RS-422/485
	Digital I/O	8-bit digital I/O	N/A
	Display	1 x VGA, 2 x HDMI	2 x VGA
	Resolution	VGA: Up to 2048 x 1536@75Hz HDMI: Up to 1920 x 1200@60Hz	VGA: Up to 1920 x 1200@60Hz
	Audio	1 x Line-out	1 x Line-out
	Wireless	1 x 802.11b/g/n (optional)	1 x 802.11b/g/n (optional)
Expansions	PCIe Mini	1 x Full-size PCIe Mini card slot with mSATA support	1 x Full-size (supports mSATA) 1 x Half-size
Power	Power Input	9 V~36 V DC Power 1: DC jack Power 2: Terminal block	9 V~36 V DC Power 1: DC jack Power 2: Terminal block
	Power Consumption	12 V@3.01 A (Intel® Celeron® dual-core 847E 1.1 GHz CPU with 4 GB DDR3 memory)	12V@1.59A (Intel® dual-core D2550 CPU with 4 GB 1333 MHz DDR3 memory)
Reliability	Mounting	Wall mount, VESA 100	Wall mount, VESA 100
	Operating Temperature	-10°C~60°C with air flow (SSD), 5% ~ 95%, non-condensing	-10°C~60°C with air flow (SSD), 5% ~ 95%, non-condensing
	Operating Shock	Half-sine wave shock 3G, 11ms, 3 shocks per axis	Half-sine wave shock 3G, 11ms, 3 shocks per axis
	Operating Vibration	MIL-STD-810F 514.5C-2 (SSD)	MIL-STD-810F 514.5C-2 (SSD)
	Weight (Net/Gross)	2.2 kg/3 kg	2.2 kg/3 kg



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## Friendly to Use



### Easy for installation

- Hinge design for rear cover
- Easy assembly of storage/memory/PCIe Mini card

### Wide range of DC power input

- ECN-360A-HM65: 9 V~36 V DC
- ECN-360A-D2550: 9 V~28 V DC

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Date:01.06.2016

Fully Integrated I/O

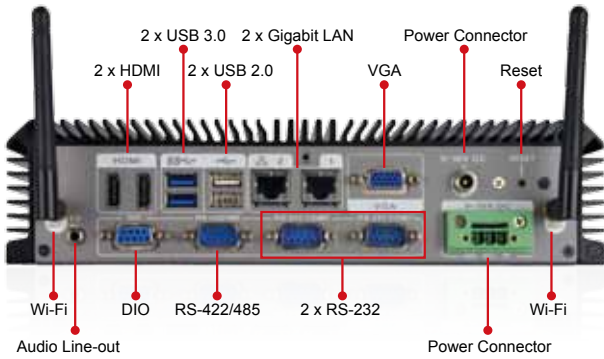
●ECN-360A-HM65 Front I/O



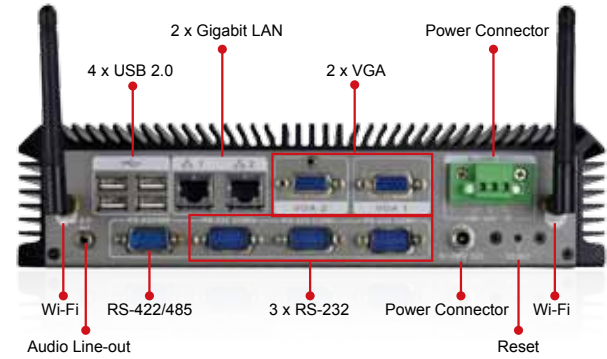
●ECN-360A-D2550 Front I/O



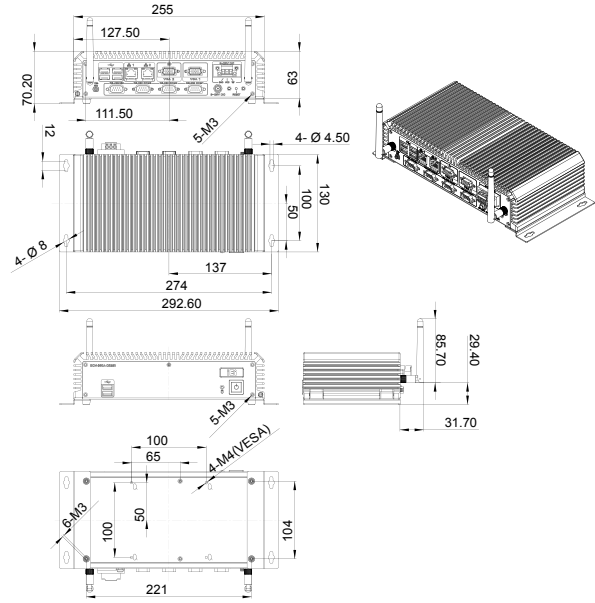
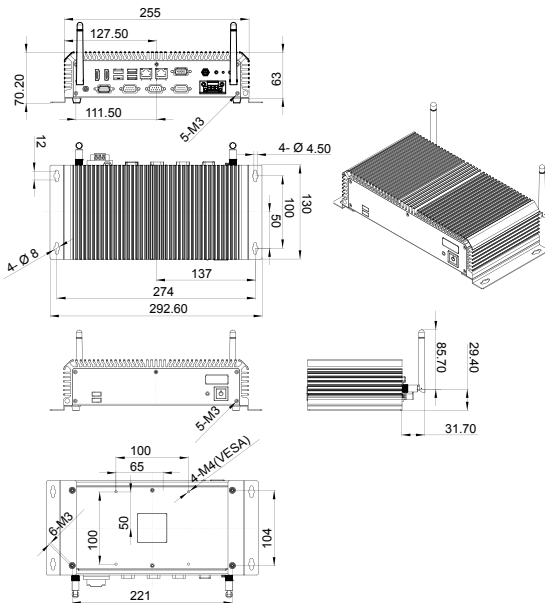
●ECN-360A-HM65 Rear I/O



●ECN-360A-D2550 Rear I/O



Dimensions (Unit: mm)



Ordering Information

Part No.	Description
ECN-360A-HM65/4G-R11	Embedded system with NANO-HM651-847E, Intel® Celeron® 847E dual-core 1.1 GHz CPU, with 2 x HDMI, 1 x VGA, 2 x RS-232, 1 x RS-422/485, 4GB DDR3 SO-DIMM pre-installed, dual Realtek LAN, DIO, 9 V~36 V DC, RoHS
ECN-360A-D2550/2G-R11	Embedded system with NANO-CV-D25502, Intel® Atom™ D2550 dual-core 1.86 GHz CPU, with 2 x VGA, 3 x RS-232, 1 x RS-422/485, 2GB DDR3 SO-DIMM pre-installed, dual Realtek LAN, 9 V~28 V DC, RoHS

Options

Part No.	Description
EMB-WIFI-KIT01-R11	1T1R Wi-Fi module kit for embedded system, 1 x Wi-Fi module, 2 x RF cable, 2 x antenna, RoHS

Packing List

1 x Power cord	1 x Screw set	1 x Utility CD
1 x Power adapter (with PSE/ErP certified)	1 x Wall mount bracket	1 x One Key Recovery CD